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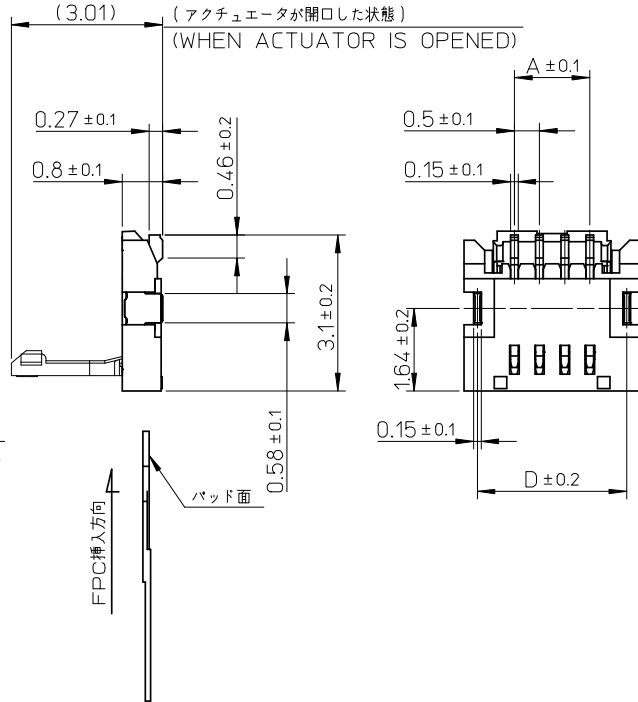
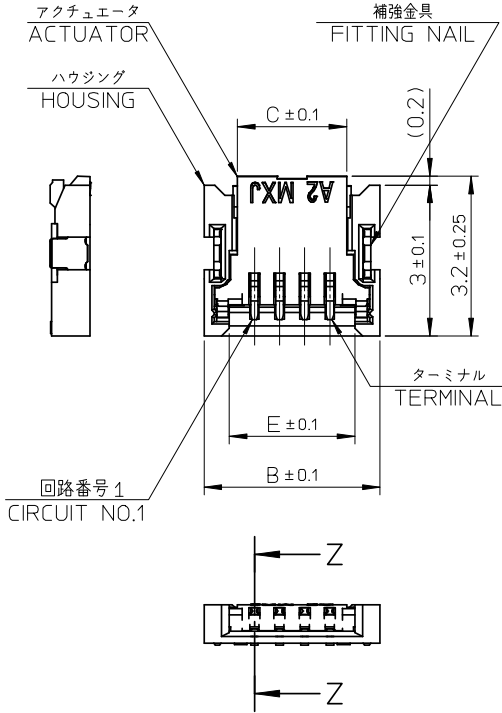
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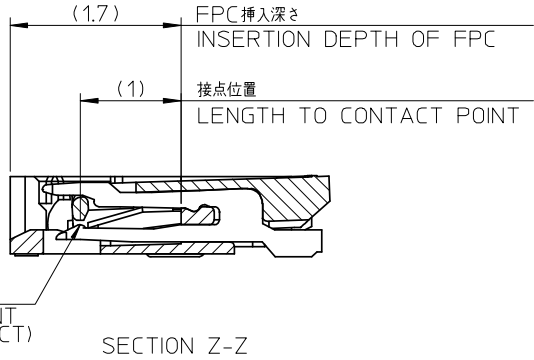
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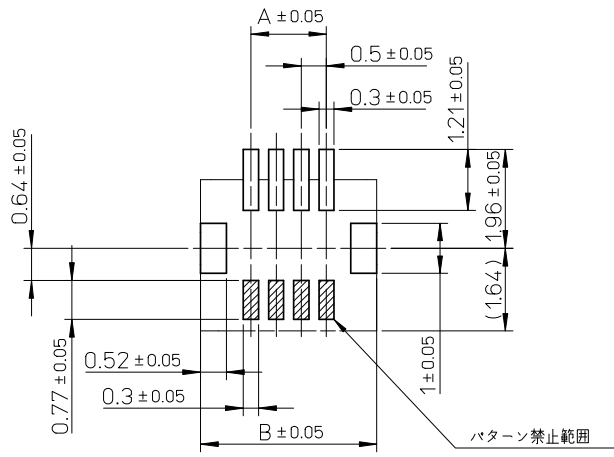
注記 NOTES:

- 材質 MATERIAL
ハウジング: 耐熱性樹脂、ガラス充填、UL94V-0
HOUSING: HEAT RESISTANCE POLYMER, GLASS FILLED, UL94V-0
アクチュエータ: 耐熱性樹脂、ガラス充填、UL94V-0
ACTUATOR: HEAT RESISTANCE POLYMER, GLASS FILLED, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
補強金具: 銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)
- めっき仕様 PLATING
ターミナル: 部分金メッキ
Terminal: PARTIAL GOLD PLATING
接点部 0.1マイクロメートル以上
半田付け部 0.05マイクロメートル以上
TERMINAL: SEPARATED GOLD PLATING
CONTACT AREA 0.1 MICROMETER MINIMUM.
SOLDER TAIL AREA 0.05 MICROMETER MINIMUM.
下地 ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.
補強金具: 錫メッキ 1.0マイクロメートル以上
NAIL: TIN PLATING 1.0 MICROMETER MINIMUM.
下地 ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.
- 平坦度は、0.1mm以下とする。
TAILS AND NAILS COPLANARITY TO BE 0.1mm MAXIMUM.

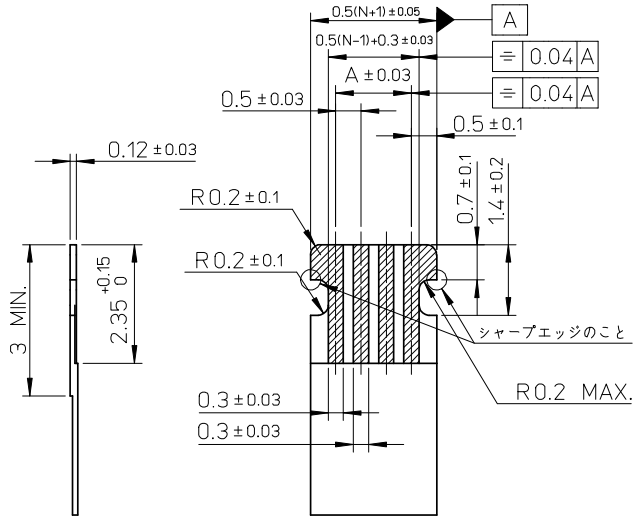


4.0	4.47	3.68	5.0	3.0	NOT AVAILABLE	NOT AVAILABLE	7
3.5	3.97	3.18	4.5	2.5	501461-0601	501461-0609	6
3.0	3.47	2.68	4.0	2.0	501461-0501	501461-0509	5
2.5	2.97	2.18	3.5	1.5	501461-0401	501461-0409	4
E	D	C	B	A	エンボス梱包品 EMBOSSED PACKAGING		製品番号 MATERIAL NO.
					ORDER No. オーダー番号		極数(N) CIRCUITS(N)

REVISED EC NO: J2008-4048 DRWN: MABEI 2008/06/13 CHKD: THARUYAMA 2008/06/16 APPR: NUKITA 2008/06/16 REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY RSUMIYA		DATE 2004/11/10	TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY -LEAD FREE-	
	10 OVER 30 UNDER	± 0.25	CHECKED BY HIRATA		DATE 2004/11/10	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY MSASAO		DATE 2004/11/10		
ANGULAR $\pm 1^\circ$		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-501461-001	SHEET NO. 1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



推奨基板寸法
RECOMMENDED P.C.BOARD PATTERN LAYOUT



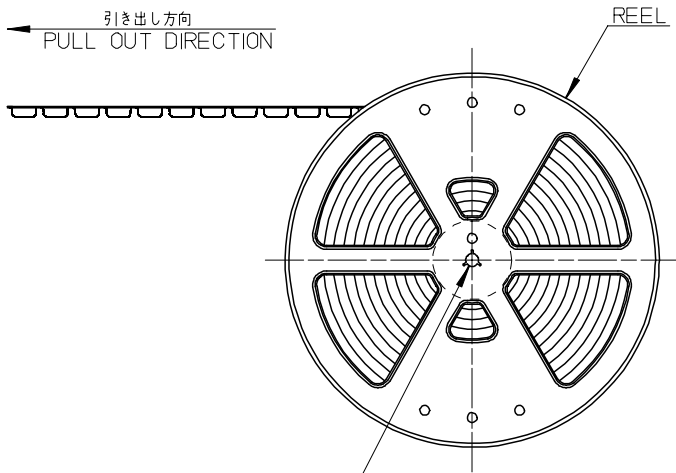
推奨FPC寸法
RECOMMENDED FPC PATTERN LAYOUT

FPCについて:
 抜き方向は、導体側から補強板側を推奨します。
 補強フィルム材質は、ポリイミドを推奨します。
 接着剤は、熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は、導通不良の原因となりますので染み出しが無いよう、お願いします。

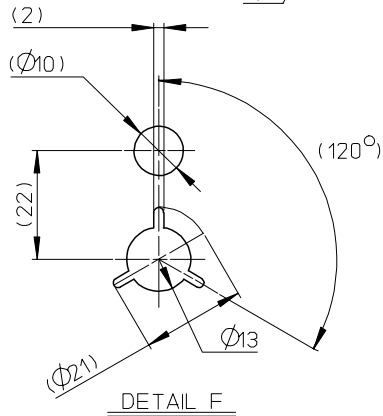
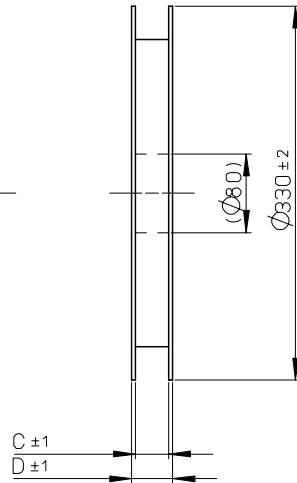
ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFNER FILME SIDE.
 RECOMMENDED MATERIAL:
 STIFFNER FILME: POLYIMIDE
 BONDING AGENT: THRMOSSETTING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ASHESIVE MAY CAUSE
 THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2008-4048 DRWN: MWABEI 2008/06/13 CHKD: THARUYAMA 2008/06/16 APPR: NUKITA 2008/06/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY RSUMIYA	DATE 2004/11/10	TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY -LEAD FREE-			
		10 OVER 30 UNDER	± 0.25	CHECKED BY HHIRATA	DATE 2004/11/10	MOLEX INCORPORATED			
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2004/11/10	DOCUMENT NO. SD-501461-001			
REV		ANGULAR ± 1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1	SIZE A3	SHEET NO. 2 OF 2			

引き出し方向
PULL OUT DIRECTION



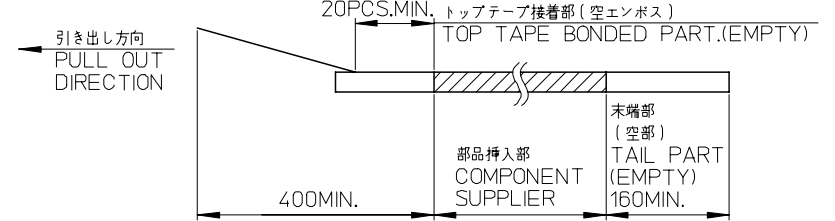
REEL



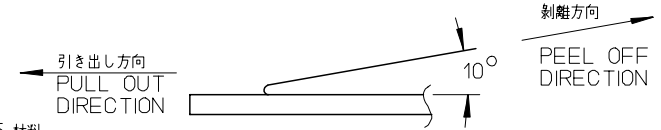
DETAIL F

NOTES

1. 製品詳細寸法については製品単体図面を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
2. 梱包数量: 3000個/リール
NUMBER OF CONNECTORS 3000PCS/REEL
3. リードテープ長さ
LEAD TAPE LENGTH



4. トップテープの剥離強度: $0.1N \sim 1.3N$ { $10gf \sim 130gf$ }
(剥離強度は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE: $0.1N \sim 1.3N$ ($10gf \sim 130gf$)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



5. 材料
MATERIAL
キャリアテープ(CARRIRE TAPE): ホリスチレン (POLYSTYRENE)
トップテープ(TOP TAPE): PET, PE, PEF
リール(REEL): ホリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAILED>

501461-**01 MODEL NO.

REVISED EC NO: J2008-0606 DRWN: A0YAGI 2007/09/06 CHKD: THARUYAMA 2007/09/10 APPR: NUKITA 2007/09/10	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± 0.2	DRAWN BY RSUMIYA	DATE 2005/02/07	TITLE 0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	± 0.25	CHECKED BY HIRATA	DATE 2005/02/07	MOLEX INCORPORATED		
	30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2005/02/07	MATERIAL NO. SEE SHEET 2	DOCUMENT NO. SD-501461-002	SHEET NO. 1 OF 2
	ANGULAR	$\pm 1^\circ$	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

10 9 8 7 6 5 4 3 2 1

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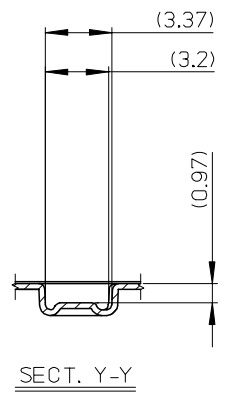
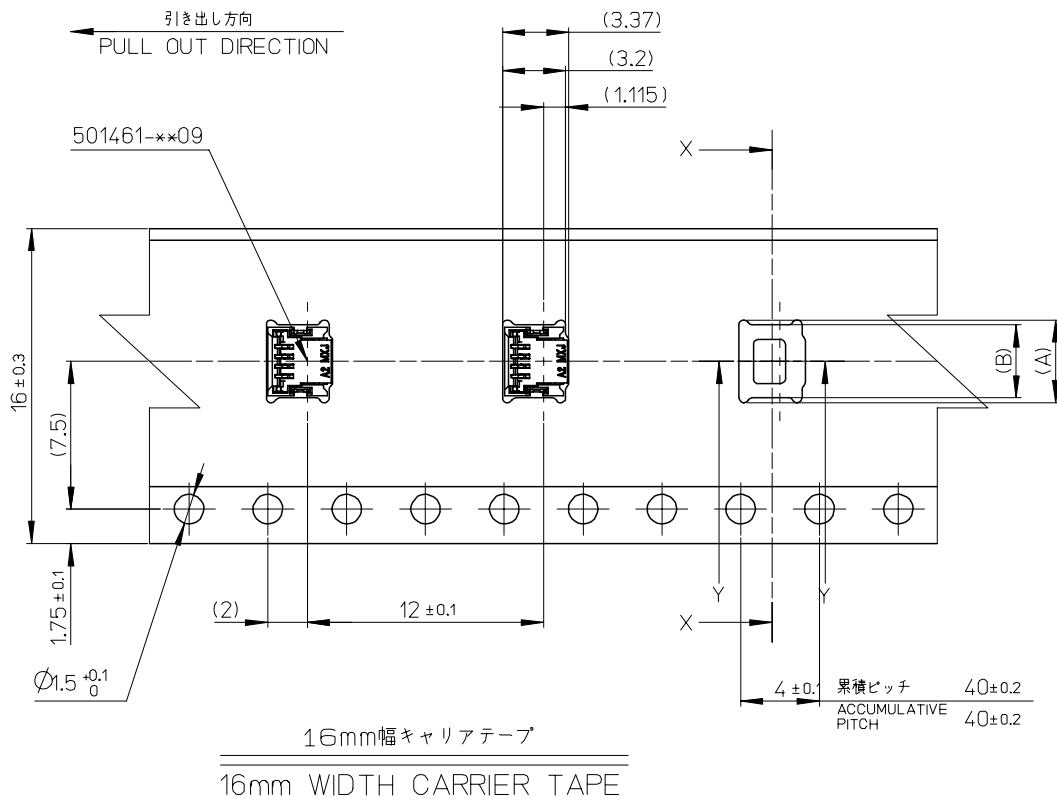
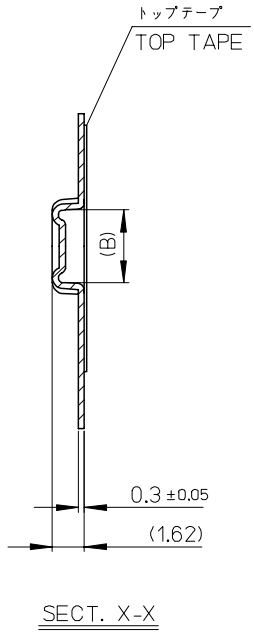
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引き出し方向
PULL OUT DIRECTION



16	21.4	17.4	5.2	5.7	NOT AVAILABLE	7	
			4.7	5.2	501461-0601	6	
			4.2	4.7	501461-0501	5	
			3.7	4.2	501461-0401	4	
キャリアテープ幅 CARRIER TAPE WIDTH		D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2008-0606 DRWN: A0YAGI 2007/09/06 CHKD: THARUYAMA 2007/09/10 APPR: NUKITA 2007/09/10	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER ± 0.2	DRAWN BY RSUMIYA	DATE 2005/02/07	TITLE 0.5 FPC CONN BACK FLIP H=0.8 EMBSTP PKG -LEAD FREE-	
	10 OVER 30 UNDER ± 0.25	CHECKED BY HIRATA	DATE 2005/02/07	MOLEX INCORPORATED	
	30 OVER ± 0.3	APPROVED BY MSASAO	DATE 2005/02/07	DOCUMENT NO. SD-501461-002	SHEET NO. 2 OF 2
	ANGULAR ± 1°	MATERIAL NO. SEE TABLE			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				